

ABSTRACT OF THE DISCLOSURE

There is provided a polishing member including photocatalyst particles that exhibit photocatalysis on light irradiation, and a support material that supports
5 the photocatalyst particles. There is also provided a method of manufacturing a semiconductor device, including polishing a surface of a workpiece that is to be used as at least a portion of the semiconductor device with the polishing member with a fluid
10 interposed between the polishing member and the surface of the workpiece while performing light irradiation onto the polishing member.